



# PATENT ABSTRACTS OF JAPAN

(11)Publication number : 04-056262

(43)Date of publication of application : 24.02.1992

(51)Int.Cl.

H01L 25/065

H01L 25/07

H01L 25/18

H01L 27/00

(21)Application number : 02-167207

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(22)Date of filing : 25.06.1990

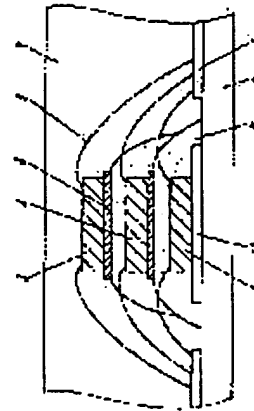
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## (54) SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE

(57)Abstract:

PURPOSE: To enable a semiconductor integrated circuit device to be miniaturized and improved in electrical properties by a method wherein two or more semiconductor chips are stacked up on a board.

CONSTITUTION: Semiconductor chips 1, 2, and 3 are stacked up on a thin Au film 10 on a board 4 and bonded, and the chips 1, 2, and 3 are connected to a wiring 6 provided onto the board 4 with bonding wires, and the chips are coated hard with resin 7 except a bonding part on the board. Then, the chip 2 is bonded with an adhesive agent 8, the chip 2 is connected to the wiring 6 provided onto the board 4 through bonding, and a process the same as above is repeated, whereby the chip 3 is connected to the wiring 6 on the board 4. Lastly, the whole body is covered with a resin 9.



## LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

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